

# **Final Product Change Notification**

Issue Date:28-Apr-2013Effective Date:14-Sep-2013

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# 201301017F01



# QUALITY

## **Change Category**

[X] Wafer Fab process [X] Wafer Fab materials

[] Wafer Fab location

[] Assembly Process [] Assembly Materials [] Assembly Location

[] Product Marking [] Electrical spec./Test coverage [] Test Location [X] Design

[] Mechanical Specification

[] Packing/Shipping/Labeling

# Release of 8 inch wafer diameter and new die design

## **Details of this Change**

Release of production using 8 inch wafer diameter and new die design for products in SOT23 and SOT323 package.

Old products: Production using 6 inch wafer diameter

Changed products: Production using 8 inch wafer diameter and new die design.

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and within the same distribution).

## Why do we Implement this Change

Increased flexibility and volume ramp-up.

## **Identification of Affected Products**

Changed products can be identified by lot No. after implementation

# **Product Availability**

#### Sample Information

Samples are available upon request Latest sample request date for PCN samples is May 24, 2013.

#### Production

Planned first shipment 01-Oct-2013

#### Impact

No change on external dimensions or mechanical behaviour. Electrical parameters are unchanged (in specification and with the same distribution).

#### **Data Sheet Revision**

No impact to existing datasheet

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

#### **Timing and Logistics**

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 28-May-2013.

#### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please <u>contact NXP "Global Quality Support</u> <u>Team"</u>.

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly: Name GA Customer Support e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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